

Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32794 ... B32798

Date: October 2011

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MKP AC filtering

Typical applications

 Output AC filtering for power converters UPS, solar inverters, motor drives

Climatic

- Max. operating temperature: 105 °C
- Climatic category (IEC 60068-1): 40/85/56

Construction

- Dielectric: Polypropylene (PP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Optimized AC voltage performance
- High ripple current/frequency capability
- Small dimensions
- For PCB mounting

Terminals

- Parallel wire leads, lead-free tinned
- 2-pin and 4-pin versions
- Standard lead lengths: 6 -1 mm
- Special lead lengths available on request

Marking

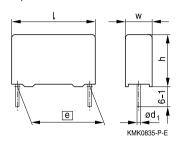
Manufacturer's logo, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage

Delivery mode

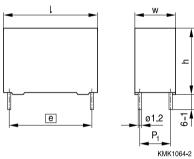
Bulk (untaped, lead length 6-1 mm)

Dimensional drawings

2-pin version



4-pin version



Dimensions in mm

Version	Lead spacing e ±0.4	Lead diameter d ₁	Туре	
2-pin	27.5	0.8	B32794D	
2-pin	37.5	1.0	B32796E/T	
4-pin	37.5	1.2	B32796G	
4-pin	52.5	1.2	B32798G	





Overview of available types

Lead spacing	27.5 mm							
Type	B32794							
Page	6			_				
V _{RMS} (V AC)	250	300	350	400				
C _R (μF)								
0.82								
1.2								
1.5								
2.0								
2.2								
2.5								
3.3								
3.5								
4.0								
5.0								
6.3								
7.5								
8.0								
10								
12								
15								





Lead spacing	37.5 mm			
Туре	B32796			
Page	7			
V _{RMS} (V AC)	250	300	350	400
C _R (μF)				
2.7				
3.5				
4.0				
5.0				
5.6				
7.5				
8.0				
10				
11				
13				
14				
15				
16				
20				
22				
24				
25				
30				
34			_	
40				
45				





Lead spacing	52.5 mm							
Туре	B32798							
Page	9							
V _{RMS} (V AC)	250	300	350	400				
C _R (μF)								
18								
20								
25								
26								
30								
35								
40								
55								
75								





MKP AC filtering

Ordering codes and packing units (lead spacing 27.5 mm)

V_{RMS}	V_R	C _R	Max. dimensions	P ₁	Ordering code	I _{RMS}	ESL	ESR	Untaped
			$w \times h \times I$		(composition see	60 °C		10 kHz	·
					below)	10 kHz			pcs./
V AC	V DC	μF	mm	mm		Α	nΗ	mΩ	MOQ
250	630	2.5	$11.0 \times 19.0 \times 31.5$	_	B32794D2255+000	4	24	14.1	2352
		4.0	$11.0 \times 21.0 \times 31.5$	_	B32794D2405+000	6	25	9.1	2352
		6.3	$15.0\times24.5\times31.5$	_	B32794D2635+000	8	26	6.1	1680
		10	$16.0 \times 32.0 \times 31.5$	_	B32794D2106+000	11	27	4.2	1064
		15	$22.0\times36.5\times31.5$	_	B32794D2156+000	13	28	3.1	784
300	700	2.0	$11.0 \times 19.0 \times 31.5$	_	B32794D3205+000	4	24	15.6	2352
		3.3	$13.5\times23.0\times31.5$	_	B32794D3335+000	6	25	9.7	1932
		5.0	$14.0\times24.5\times31.5$	_	B32794D3505+000	7	26	6.7	1848
		8.0	$18.0\times33.0\times31.5$	_	B32794D3805+000	9	27	4.6	952
		12	$22.0\times36.5\times31.5$	_	B32794D3126+000	11	28	3.5	784
350	875	1.2	$11.0 \times 19.0 \times 31.5$	_	B32794D8125+000	3	24	21.2	2352
		2.2	$12.5 \times 21.5 \times 31.5$	_	B32794D8225+000	5	25	11.9	2100
		3.3	$15.0\times24.5\times31.5$	_	B32794D8335+000	7	26	8.2	1680
		5.0	$18.0\times33.0\times31.5$	_	B32794D8505+000	9	27	5.8	952
		7.5	$22.0\times36.5\times31.5$	-	B32794D8755+000	12	28	4.5	784
400	1050	0.82	$11.0 \times 19.0 \times 31.5$	_	B32794D4824+000	3	24	26.5	2352
		1.5	$13.5\times23.0\times31.5$	_	B32794D4155+000	4	25	14.8	1932
		2.2	$14.0\times24.5\times31.5$	_	B32794D4225+000	6	26	10.4	1848
		3.5	$18.0\times33.0\times31.5$	_	B32794D4355+000	8	27	6.9	952
-		5.0	$22.0\times36.5\times31.5$	_	B32794D4505+000	11	28	5.5	784

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$



MKP AC filtering



Ordering codes and packing units (lead spacing 37.5 mm)

$\overline{V_{RMS}}$	V_R	C _R	Max. dimensions	P ₁	Ordering code	I _{RMS}	FSI	ESR	Untaped
▼ HMS	▼ H	Он	$\mathbf{w} \times \mathbf{h} \times \mathbf{l}$	' 1	(composition see	60 °C	LOL	10 kHz	Uniapeu
			W A II A I		below)	10 kHz		10 14 12	pcs./
V AC	V DC	μF	mm	mm	20.011)	A	nΗ	mΩ	MOQ
250	630	8	24.0 × 15.0 × 41.5	_	B32796T2805+000	8	21	9	1040
		11	24.0 × 19.0 × 41.5	_	B32796T2116+000	10	23	8	780
		22	$20.0 \times 39.5 \times 42.0$	10.2	B32796G2226+000	15	30	3.2	640
		22	$20.0 \times 39.5 \times 42.0$	_	B32796E2226+000	14	30	3.2	640
		25	28.0 × 37.0 × 42.0	10.2	B32796G2256+000	17	30	2.9	440
		25	$28.0 \times 37.0 \times 42.0$	_	B32796E2256+000	16	30	2.9	440
		40	$30.0 \times 45.0 \times 42.0$	20.3	B32796G2406+000	21	33	2.3	400
		40	$30.0 \times 45.0 \times 42.0$	_	B32796E2406+000	20	33	2.3	400
		45	$33.0 \times 48.0 \times 42.5$	20.3	B32796G2456+000	23	33	1.9	180
300	700	5.6	24.0 × 15.0 × 41.5	_	B32796T3565+000	7	21	12	1040
		7.5	$24.0 \times 19.0 \times 41.5$	_	B32796T3755+000	9	23	10	780
		16	$20.0\times39.5\times42.0$	10.2	B32796G3166+000	14	30	3.9	640
		16	$20.0 \times 39.5 \times 42.0$	_	B32796E3166+000	13	30	3.9	640
		20	$28.0 \times 37.0 \times 42.0$	10.2	B32796G3206+000	15	30	3.1	440
		20	$28.0 \times 37.0 \times 42.0$	_	B32796E3206+000	14	30	3.1	440
		30	$30.0 \times 45.0 \times 42.0$	20.3	B32796G3306+000	19	33	2.2	400
		30	$30.0 \times 45.0 \times 42.0$	_	B32796E3306+000	18	33	2.2	400
		34	$33.0\times48.0\times42.5$	20.3	B32796E3346+000	20	33	1.9	180
350	875	4	$24.0 \times 15.0 \times 41.5$	_	B32796T8405+000	7	21	13	1040
		5	$24.0 \times 19.0 \times 41.5$	_	B32796T8505+000	9	23	11	780
		10	$20.0 \times 39.5 \times 42.0$	10.2	B32796G8106+000	12	30	4.9	640
		10	$20.0 \times 39.5 \times 42.0$	_	B32796E8106+000	11	30	4.9	640
		14	$28.0 \times 37.0 \times 42.0$	10.2	B32796G8146+000	15	30	3.6	440
		14	$28.0 \times 37.0 \times 42.0$	_	B32796E8146+000	14	30	3.6	440
		15	$30.0 \times 45.0 \times 42.0$	20.3	B32796G8156+000	15	30	3.0	400
		20	$30.0 \times 45.0 \times 42.0$	20.3	B32796G8206+000	19	30	2.6	400
		20	$30.0 \times 45.0 \times 42.0$	_	B32796E8206+000	18	30	2.6	400
		24	$33.0\times48.0\times42.5$	20.3	B32796G8246+000	20	30	2.5	180

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$





MKP AC filtering

Ordering codes and packing units (lead spacing 37.5 mm)

V_{RMS}	V_R	C _R	Max. dimensions	P ₁	Ordering code	I _{RMS}	ESL	ESR	Untaped
			$w \times h \times I$		(composition see	60 °C		10 kHz	
					below)	10 kHz			pcs./
V AC	V DC	μF	mm	mm		Α	nΗ	mΩ	MOQ
400	1050	2.7	$24.0 \times 15.0 \times 41.5$	_	B32796T4275+000	7	21	15	1040
		3.5	$24.0 \times 19.0 \times 41.5$	_	B32796T4355+000	8	23	13	780
		7.5	$20.0 \times 39.5 \times 42.0$	10.2	B32796G4755+000	11	30	5.5	640
		7.5	$20.0 \times 39.5 \times 42.0$	_	B32796E4755+000	10	30	5.5	640
		10	$28.0 \times 37.0 \times 42.0$	10.2	B32796G4106+000	14	30	4.5	440
		10	$28.0 \times 37.0 \times 42.0$	_	B32796E4106+000	13	30	4.5	440
		13	$30.0 \times 45.0 \times 42.0$	20.3	B32796G4136+000	17	33	3.5	400
		13	$30.0 \times 45.0 \times 42.0$	_	B32796E4136+000	16	33	3.5	400
		16	$33.0\times48.0\times42.5$	20.3	B32796G4166+000	18	33	3.5	180

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

K = +10%



MKP AC filtering



Ordering codes and packing units (lead spacing 52.5 mm)

V _{RMS}	V_R	C _R	Max. dimensions	P ₁	Ordering code	I _{RMS}	ESL	ESR	Untaped
			$w \times h \times I$		(composition see	60 °C		10 kHz	·
					below)	10 kHz			pcs./
V AC	V DC	μF	mm	mm		Α	nΗ	mΩ	MOQ
250	630	55	$30.0\times45.0\times57.5$	20.3	B32798G2556+000	21	35	2.7	280
		75	$35.0 \times 50.0 \times 57.5$	20.3	B32798G2756+000	25	38	2.1	108
300	700	40	$30.0\times45.0\times57.5$	20.3	B32798G3406+000	19	35	3.2	280
		55	$35.0\times50.0\times57.5$	20.3	B32798G3556+000	24	38	2.5	108
350	875	26	$30.0\times45.0\times57.5$	20.3	B32798G8266+000	18	35	4.5	280
		30	$35.0 \times 50.0 \times 57.5$	20.3	B32798G8306+000	20	37	4.0	108
		35	$35.0 \times 50.0 \times 57.5$	20.3	B32798G8356+000	22	38	3.0	108
		40	$35.0 \times 50.0 \times 57.5$	20.3	B32798G8406K000	22	38	3.0	108
400	1050	18	$30.0\times45.0\times57.5$	20.3	B32798G4186+000	16	35	4.7	280
		20	$35.0\times50.0\times57.5$	20.3	B32798G4206+000	17	37	4.5	108
		25	$35.0 \times 50.0 \times 57.5$	20.3	B32798G4256+000	20	38	3.5	108

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$





MKP AC filtering

Technical data

Deference standard: IEC 610	71. EN 61071. VDE 0560-120
neierence standard, ieu o id	/ I. EN 0 IU/ I. VDE 0300-120

Operating temperature	range (case)	Max. operating temperature, T _{op,m}	_{nax} +105 °C		
		Upper category temperature T _{max}	+85 °C		
		Lower category temperature T _{min}	–40 °C		
		Note: At T > 85 °C de-rating for			
		V _{RMS} (V AC) should be 1.5%/°C			
Capacitance drift in ran	ge	2% respect the value measured a	at reference conditions		
(−40 °C, −85 °C)					
Insulation Resistance F	R _{ins}	30 000 s			
given as time constant					
$\tau = C_R \cdot R_{ins}$, rel. humid	ity ≤ 65%				
(minimum as-delivered	values)				
Test voltage between te	erminals	1.5 · V _R for 10 s			
•		1.65 · V _R for 2 s			
DC test voltage termina	al to case (10 s)	2 · V _{RMS} + 1000 V AC (min. 2000	V AC) at 50 Hz		
Maximum permissible of	overvoltage for	1.3 · V _{RMS}			
short operating periods	-				
Maximum peak current	(A)	$I_{P,max} = C_R \cdot \frac{dV}{dt}$			
Damp heat test		56 days/40 °C/93% relative humid	dity		
Limit values after damp	heat test	Capacitance change I ∆C/C I	≤ 5%		
		Dissipation factor change Δ tan δ	≤ 1.5 · 10 ⁻³ (at 1 kHz)		
		Insulation resistance R _{ins}	≥ 50% of minimum		
		113	as-delivered values		
Change of temperature		In accordance with IEC 60068-2-14 (Test Nb)			
Reliability:	Failure rate λ	300 fit			
	Service life t _{st}	> 60 000 h at V _{RMS}			
	OCIVIOC IIIC ISL	For conversion to other operating	conditions refer to		
		chapter "Reliability" on page 439			
		enapter remarmity on page 100			
	Failure criteria:				
	Total failure	Short/open circuit			
	Failure due to	Capacitance change ∆C/C	≥ 10%		
	variation of	Dissipation factor change Δ tan δ	> 4 · upper limit value		
	parameters	Insulation resistance R _{ins}	< 1500 MΩ		
	•	incalation robotation ri _{ins}	(C _B ≤0.33μF)		
		or time constant $\sigma = C$	· · · ·		
		or time constant $\tau = C_R \cdot R_{ins}$	$< 500 \text{ s } (C_R > 0.33 \mu\text{F})$		



MKP AC filtering



Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

Note:

The values of dV/dt provided below must not be exceeded in order to avoid damaging the capacitor.

Lead spacing	27.5 mm			37.5 mm			52.5 mm					
Туре	B32794			B32796			B32798					
V _{RMS} (V AC)	250	300	350	400	250	300	350	400	250	300	350	400
		dV/dt in V/μs										
	27	31	39	47	19	21	26	32	12	14	18	21

Notes: Please take all additional data not mentioned above from our Data Book 2009 **Mounting guidelines**

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

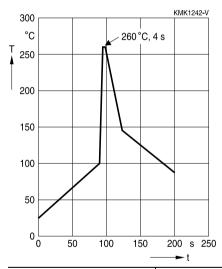
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	Solder bath temperature	Soldering time





MKT	boxed (except 2.5 \times 6.5 \times 7.2 mm) coated	260 ±5 °C	10 ±1 s
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)



Immersion depth	2.0 + 0/-0.5 mm from capacitor body or seating plane	
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder	
Evaluation criteria:		
Visual inspection	No visible damage	
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors	
tan δ	As specified in sectional specification	



MKP AC filtering



1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





MKP AC filtering

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"





MKP AC filtering

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
$lpha_{ extsf{C}}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
ΔC/C	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
ΔV/Δt	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
	Fragues Visit for radicing permissible	Wechselspannung
f ₂	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen
	Ao voltage due to current infint	Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur
. ט		Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



MKP

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i _z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_{i}	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_{S}	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
$tan \ \delta$	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Ambient temperature	Umgebungstemperatur
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t _{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
01	and voltage	-spannung
T_{op}	Operating temperature	Beriebstemperatur
T _R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung





Symbol	English	German
V _C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{o}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
ν̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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